

**Edition Ltd.**  
(Incorporated in Singapore)  
(Company Registration No. 200411873E)

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**UPDATE ON THE TENURE OF THE AGGREGATE LOAN PRINCIPAL OF S\$1,687,500 EXTENDED BY EDITION LTD. TO HYPERLYNC TECHNOLOGIES LIMITED AND THE SCHEDULED PAYMENTS**

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**1. INTRODUCTION**

The Board of Directors (the **“Board”**) of Edition Ltd. (the **“Company”**, together with its subsidiaries, the **“Group”**) refers to its announcements on:

- (a) 5 June 2018 in relation to the Binding Memorandum of Understanding (**“MOU”**) entered by the Company with Hyperlync Technologies Limited (**“Hyperlync”**) to acquire a 51% stake in the enlarged share capital of Hyperlync;
- (b) 13 August 2018 in relation to the entry into the Supplemental Loan Agreement to amend the Loan Agreement with Hyperlync;
- (c) 12 December 2018 in relation to the termination of the MOU and entry into the Second Supplemental Loan Agreement to further amend the Loan Agreement;
- (d) 11 June 2019 in relation to an update on the extension of the tenure of the loan of an aggregate principal amount of S\$1,687,500 (**“Loan”**) extended by the Company to Hyperlync;
- (e) 5 July 2019 in relation to the entry into the Third Supplemental Loan Agreement to further amend the Loan Agreement;
- (f) 12 June 2020 in relation to an update on the extension of the tenure of the loan of an aggregate principal amount of S\$1,687,500 extended by the Company to Hyperlync;
- (g) 26 June 2020 in relation to the entry into the Fourth Supplemental Loan Agreement to further amend the Loan Agreement (**“26 June 2020 Announcement”**); and
- (h) 10 February 2021 in relation to the update on Hyperlync’s scheduled payments to the Company.

(Collectively, the **“Announcements”**).

*Unless otherwise defined herein, all capitalised terms and references used herein shall bear the same meaning ascribed to them in the Announcements.*

## **2. UPDATE ON THE TENURE OF THE LOAN AND THE SCHEDULED PAYMENTS**

The Board wishes to announce that the maturity date of the Loan Agreement has been extended from 11 June 2021 till such time Hyperlync is able to repay the Loan. Pending the full repayment of the Loan, Hyperlync will pay, on a monthly basis, no less than S\$50,000, which will be applied to the repayment of the Loan principal and a late payment interest rate of an additional 1% per month, over and above the existing 12% interest per annum for the unpaid balance of the Loan.

With reference to paragraphs 3(a), 3(b) and 3(c) of the 26 June 2020 Announcement, the Board wishes to inform that following the last partial payment of S\$9,500 on 26 January 2021, Hyperlync had paid a further S\$13,000 on 22 June 2021. This S\$13,000 will be applied to the repayment of Loan principal. To-date, the cumulative total interest paid and principal repaid by Hyperlync is S\$406,450.00 and S\$13,000.00 respectively. As the Loan principal and accrued interest remain unpaid as at 11 June 2021, pursuant to the Fourth Supplemental Loan Agreement, the accrued interest has been converted to part of the Loan Principal. Accordingly, the revised outstanding principal is S\$1,800,250.

The Company continues to monitor the situation closely and will update shareholders as and when the situation requires.

## **3. CAUTIONARY STATEMENT**

Shareholders and potential investors should exercise caution when trading in the Company's shares, as there is no certainty that completion will take place. In the event of any doubt as to the action they should take, Shareholders and potential investors should consult their financial, tax, legal or other professional advisors.

**By Order of the Board  
Edition Ltd.**

Ong Boon Chuan  
Executive Director and Chief Executive Officer  
25 June 2021

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*This announcement has been reviewed by the Company's Sponsor, SAC Capital Private Limited (the "Sponsor"). It has not been examined or approved by the Singapore Exchange Securities Trading Limited (the "Exchange") and the Exchange assumes no responsibility for the contents of this announcement, including the correctness of any of the statements or opinions made or reports contained in this announcement.*

*The contact person for the Sponsor is Ms Tay Sim Yee (Telephone no.: (65) 6232 3210) at 1 Robinson Road, #21-00 AIA Tower, Singapore 048542.*